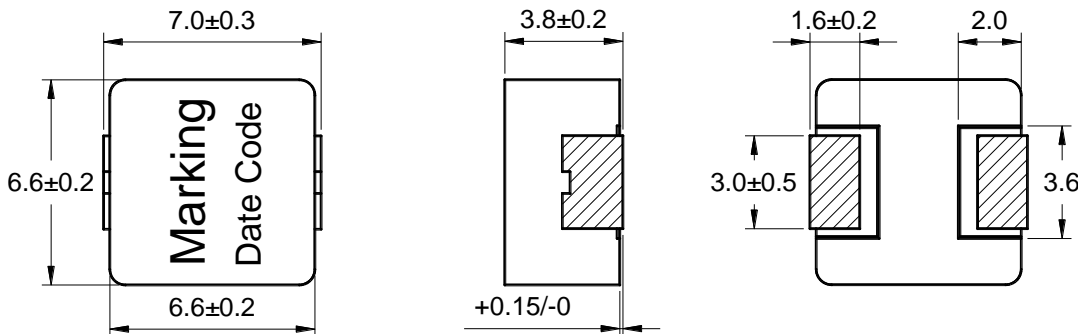


Outline: 产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI).
磁屏蔽结构：抗电磁干扰(EMI)性能强。
- A composite structure, ultra low buzz noise.
一体成型结构，超低蜂鸣噪音。
- Low loss, high efficiency, wide application frequency.
低损耗，高效率，应用频率宽。
- Lightweight design, save space, suitable for high density SMT.
轻薄型设计，节省空间，适合高密度贴装。
- Die-casting by low loss alloy powder: low impedance, small parasitic capacitance.
低损耗合金粉末压铸：低阻抗，寄生电容小。
- Operating temperature : -40°C ~ +125°C (Including coil's temperature rise)
工作温度：-40°C ~ +125°C (包含线圈发热)

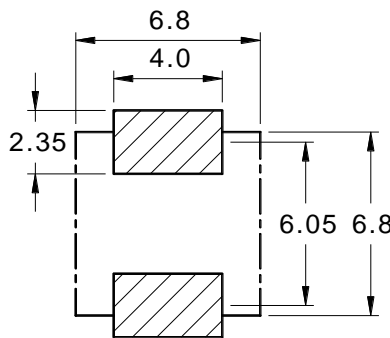
1 Appearance and dimensions (mm) 外形尺寸



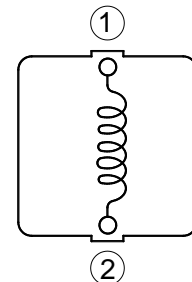
2 Marking 印字标识



3 Reference land pattern (mm) 参考基板尺寸



4 Schematic 原理图



5 Electrical characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
CSAB0740-R13M	0.13	0.60	0.80	50.0	44.0
CSAB0740-R15M	0.15	0.65	0.80	50.0	42.0
CSAB0740-R22M	0.22	1.15	1.30	35.0	32.0
CSAB0740-R33M	0.33	2.60	3.30	27.0	21.0
CSAB0740-R36M	0.36	2.50	3.10	25.0	21.5
CSAB0740-R47M	0.47	3.25	3.60	21.0	19.0
CSAB0740-R68M	0.68	4.10	4.80	21.0	17.0
CSAB0740-1R0M	1.00	5.50	6.60	18.5	14.6
CSAB0740-1R5M	1.50	7.70	9.50	12.5	12.4
CSAB0740-1R8M	1.80	9.20	11.2	13.0	11.4
CSAB0740-2R2M	2.20	11.0	15.0	11.0	10.4
CSAB0740-3R3M	3.30	16.6	20.0	9.50	8.40
CSAB0740-4R7M	4.70	27.3	30.0	9.00	6.50
CSAB0740-5R6M	5.60	36.5	38.0	7.00	5.70
CSAB0740-6R8M	6.80	40.6	50.0	6.00	5.40
CSAB0740-8R2M	8.20	47.5	55.0	6.00	5.00
CSAB0740-100M	10.0	51.5	65.0	6.00	4.80
CSAB0740-150M	15.0	86.3	95.0	4.50	3.70
CSAB0740-220M	22.0	107	125	4.00	3.30
CSAB0740-330M	33.0	199	220	3.00	2.40
CSAB0740-390M	39.0	244	280	2.80	2.20
CSAB0740-470M	47.0	256	298	2.50	2.10

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C条件下测试。

※1 Inductance measure condition at 100kHz, 1V.

电感测试条件为 100kHz, 1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流: 电感值下降其初始值的 30%时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).

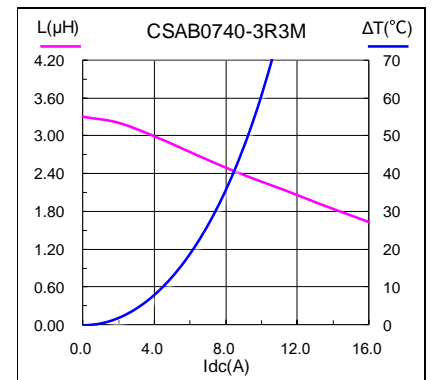
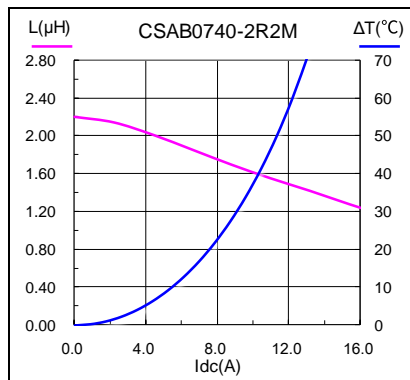
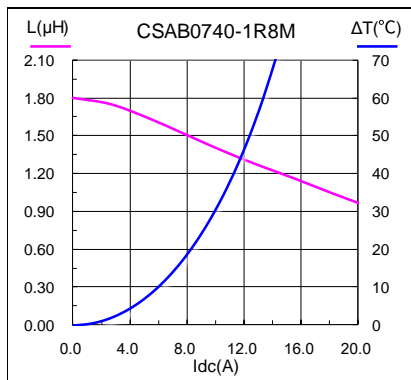
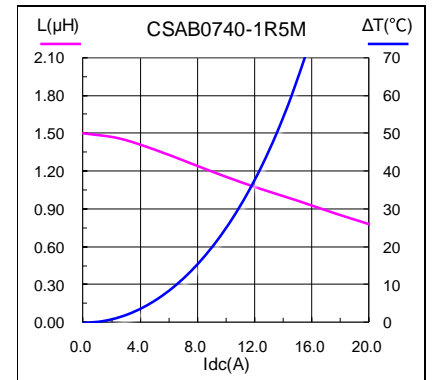
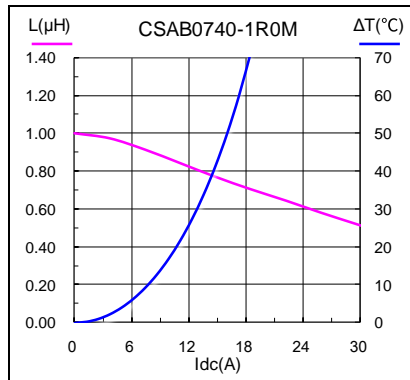
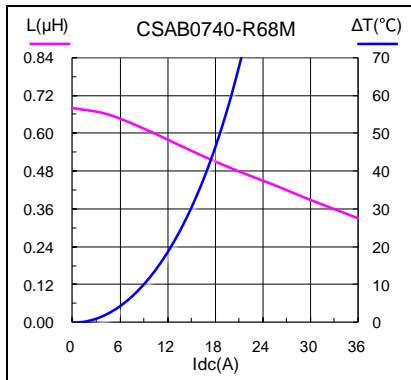
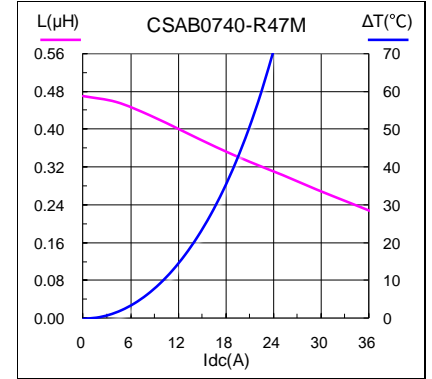
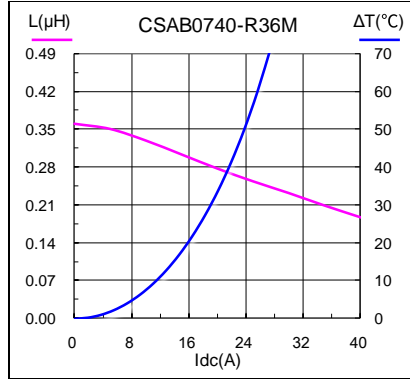
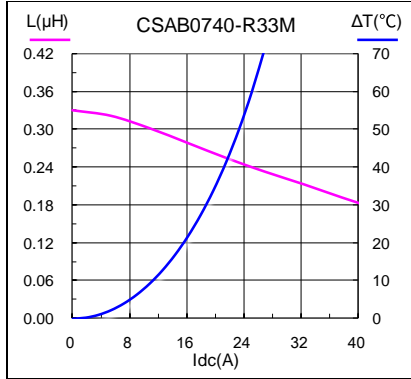
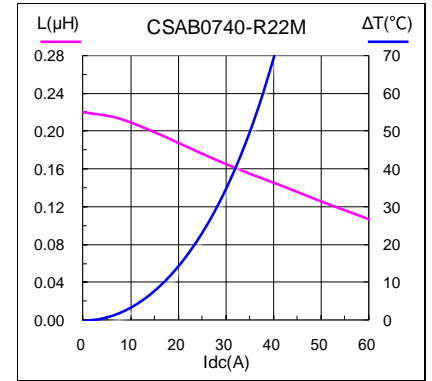
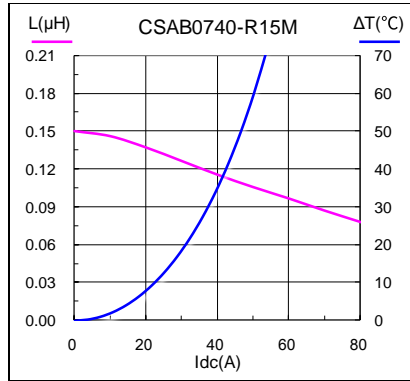
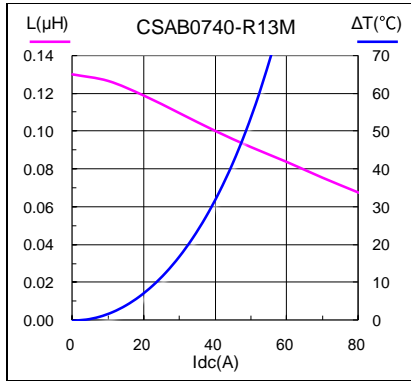
温升电流: 使产品温度上升到 ΔT40°C时所加载的实际直流电流值(Ta=25°C)。

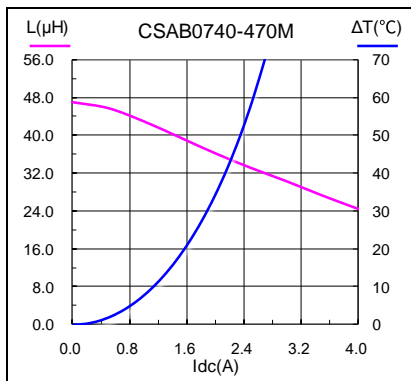
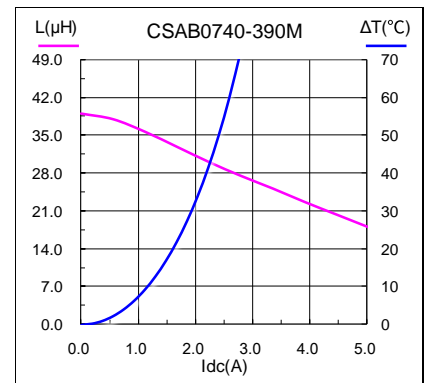
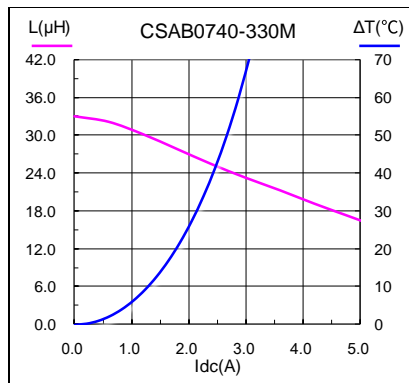
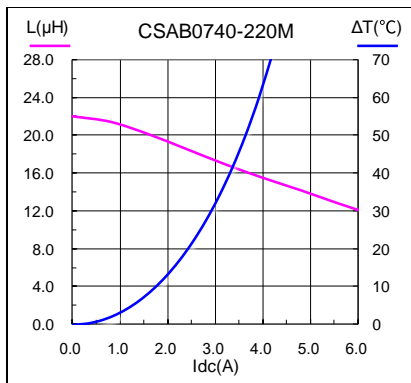
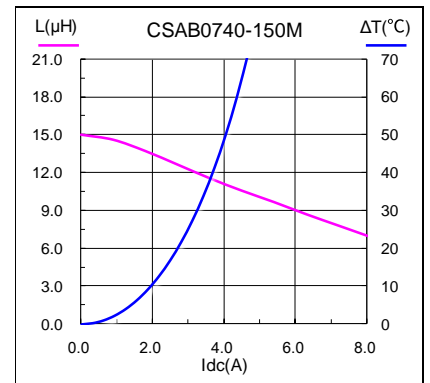
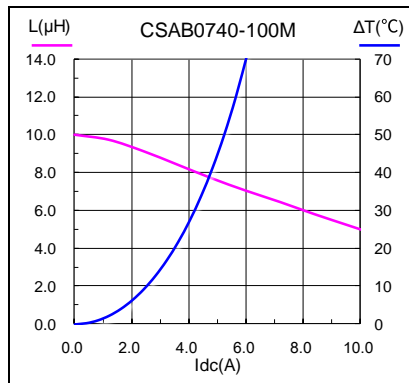
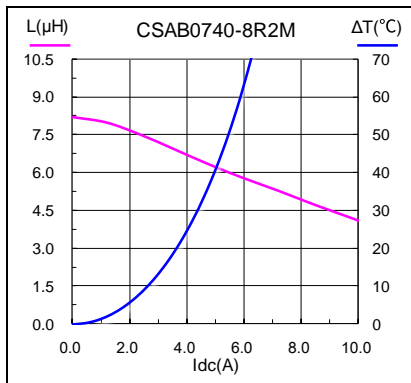
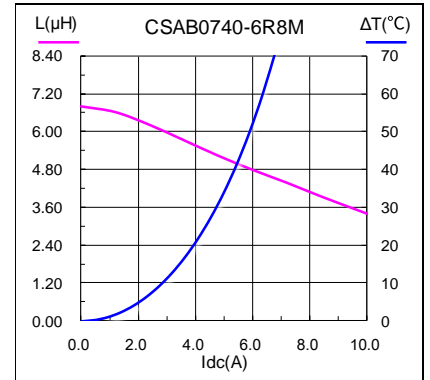
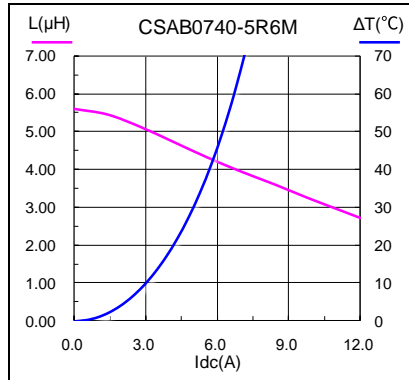
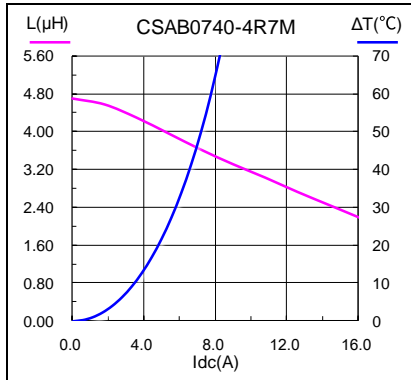
※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。

6 Saturation current VS temperature rise current curve 饱和电流 VS 温升电流曲线



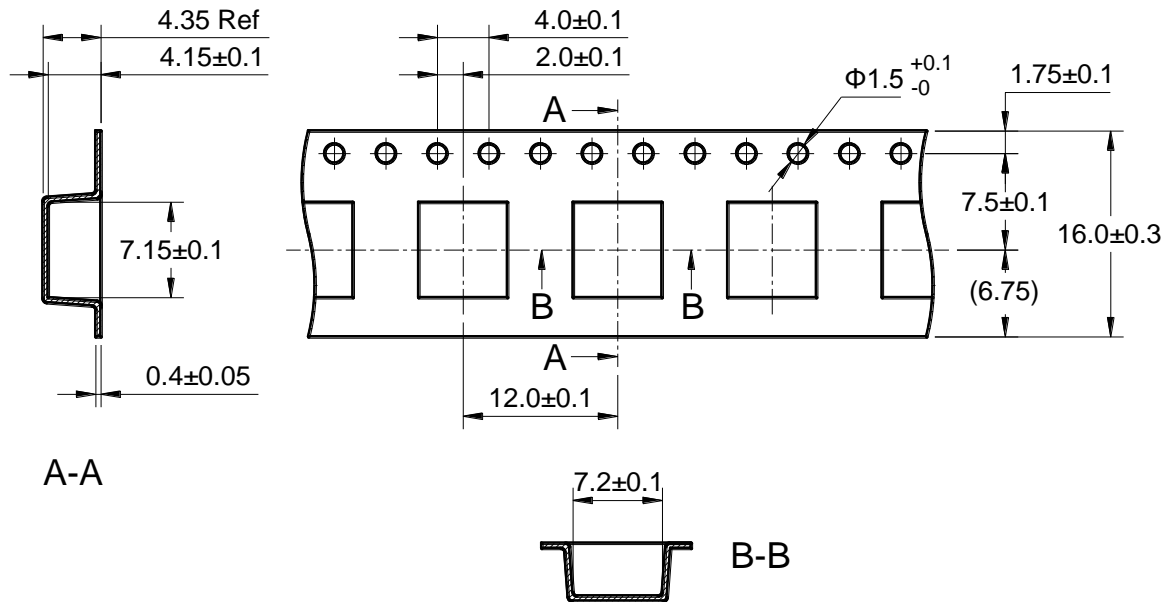


7 Packing specification

包装规格

7.1 Carrier tape dimensions (mm)

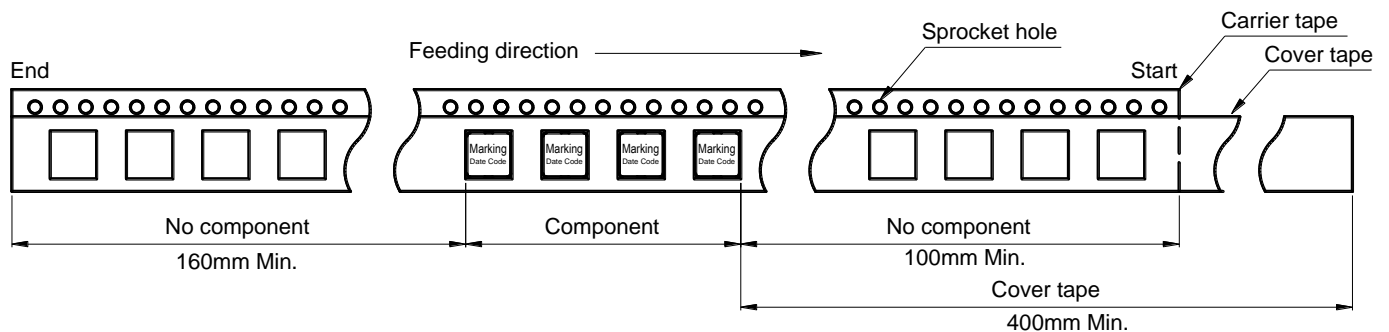
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction

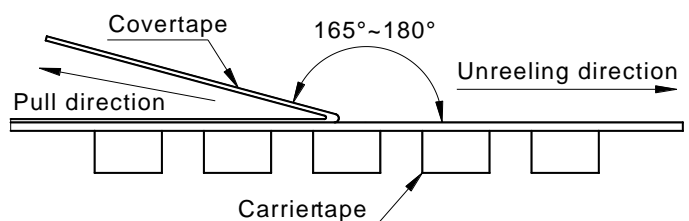
捆包方向



7.3 Cover tape peel off condition

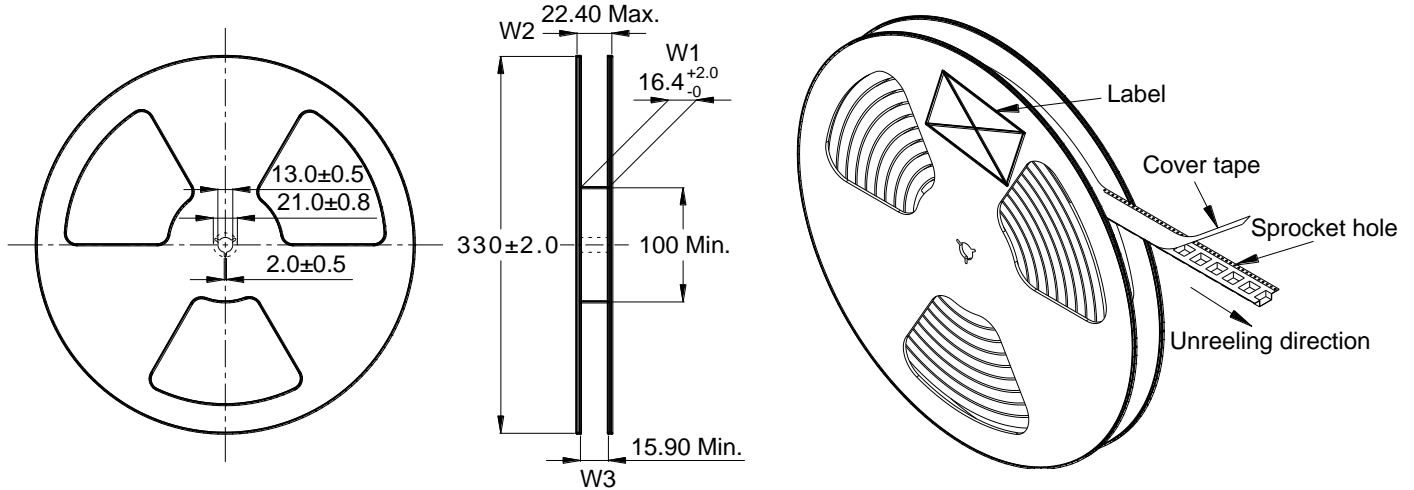
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。



7.4 Reel dimensions (mm)

卷盘尺寸



7.5 Carton dimensions and packing quantity

包装箱尺寸和包装数量

■ Inner Carton: 340×340×95mm
内包装盒

■ Out Carton : 355×355×385mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSAB0740	1000pcs	(1000×3) = 3000pcs	(3000×3) = 9000pcs

7.6 Label making

标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Part No. 产品型号
■ Electrical Information 产品电性信息
■ Quantity 数量
■ Packing No. 包装流水号

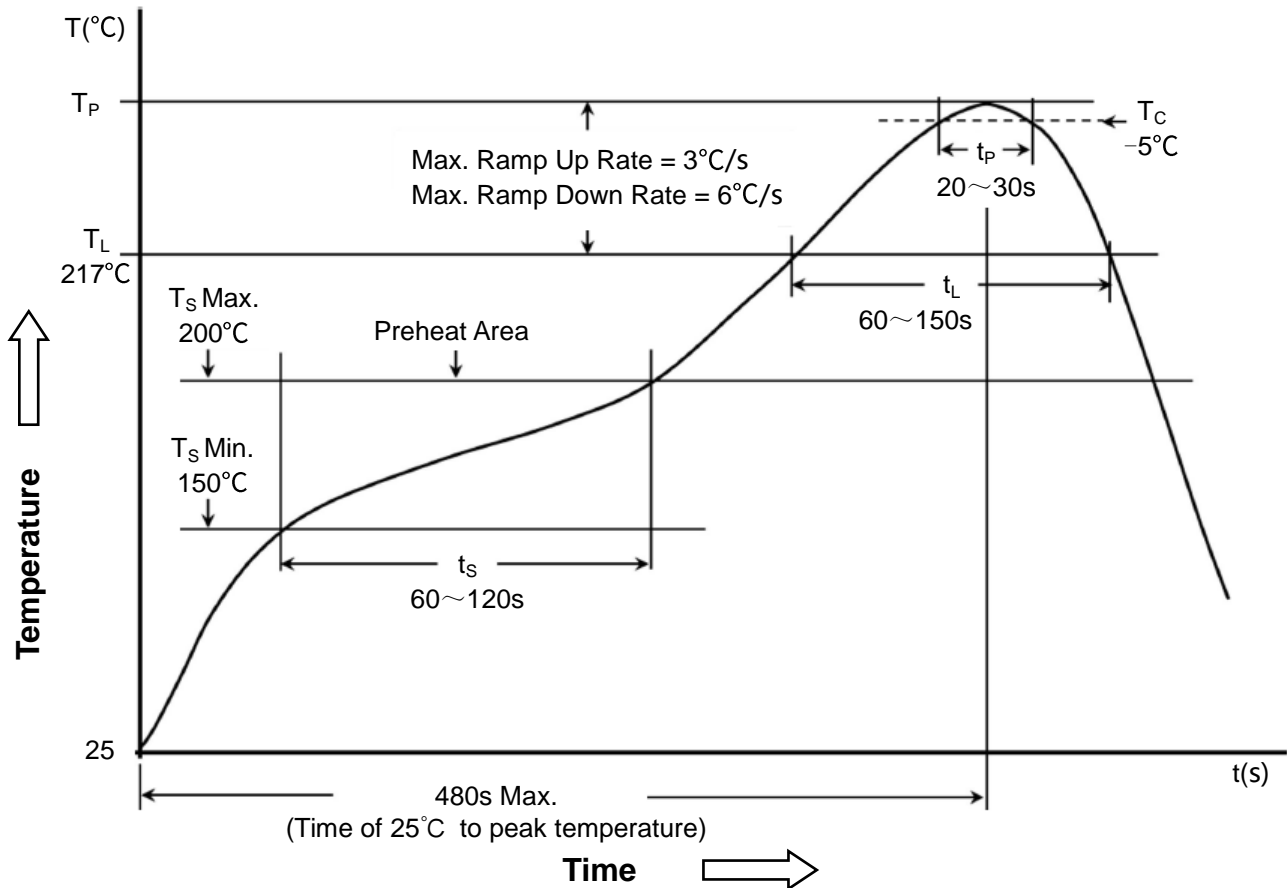
Shipping Label 运输标签
■ Customer Name 客户名称
■ Customer Part No. 客户型号
■ Supplier Part No. 供应商型号
■ Supplier Name 供应商名称
■ Country of origin 产品产地

8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。